

PACKAGE MATERIAL DECLARATION DATASHEET

Cypress Package Code	SZ	Body Size (mil/mm)	208 mils
Package Weight – Site 1	B1: 136.9000mg B2: 137.9890mg B3: 136.900mg		

SUMMARY

The 8L- SOIC EIAJ package is qualified at one assembly site. Cypress guarantees that as long as products are being ordered with a Cypress Part Number containing an "X" (e.g. CY7C1328G-133AXI, CY2308SXC-1HT) they meet the requirement of RoHS.

**ASSEMBLY Site 1: UTAC Thailand Limited (UTL)
Package Qualification Report # 140502, 144502 (Note 1)**

I. DECLARATION OF PACKAGED UNITS

A. BANNED SUBSTANCES

Materials from Level A of the EIA/JIG/JGPSSI/EICTA Material Composition Declaration Guide and EU RoHS. Listed in the table below are materials that are neither contained nor intentionally added to this product.

Substances / Compounds	Weight by mg	PPM	Analysis Report Link/s
Cadmium and Cadmium Compounds	0	< 5.0	CoA-SZ8-UTAC
Hexavalent Chromium and its Compounds	0	< 5.0	
Lead and Lead Compounds	0	< 5.0	
Mercury and Mercury Compounds	0	< 5.0	
Polybrominated Biphenyls (PBB)	0	< 5.0	
Polybrominated Diphenylethers (PBDE)	0	< 5.0	
Asbestos	0	0	As per MSDS
Azo colorants	0	0	As per MSDS
Ozone Depleting Substances	0	0	As per MSDS
Polychlorinated Biphenyls (PCBs)	0	0	As per MSDS
Polychlorinated Napthalenes	0	0	As per MSDS
Radioactive Substances	0	0	As per MSDS
Shortchain Chlorinated Paraffins	0	0	As per MSDS
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	0	0	As per MSDS
Tributyl Tin Oxide (TBTO)	0	0	As per MSDS
Formaldehyde	0	0	As per MSDS

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.

Note 2: Report available from Cypress Sales Offices or Distributors.

Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered "non-existent in the product". In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information.

Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

**B1. MATERIAL COMPOSITION (Note 3)
USING COPPER PALLADIUM WIRE**

Material	Purpose of Use	Substance Composition	CAS Number	Weight by mg	% Weight of Substance per Homogeneous Material	PPM	% Weight of Substance per Package
Leadframe	Base Material	Iron	7439-89-6	60.5300	97.3600%	442,122	44.2100%
		Phosphorus	7723-14-0	1.4600	2.3500%	10,672	1.0700%
		Zn	7440-66-6	0.0100	0.0100%	45	0.0050%
		Cu	7740-50-8	0.0500	0.0800%	375	0.0400%
		Ag	7440-22-4	0.0800	0.1300%	568	0.0600%
		Pb	7439-92-1	0.0500	0.0800%	341	0.0300%
Lead Finish	External Plating	Sn	7440-31-5	7.4590	100.0000%	54486	5.4500%
Die Attach	Adhesive	Silver	7440-22-4	0.1800	73.0000%	1317	0.1300%
		exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	0.0500	20.0000%	361	0.0400%
		1,1'-(1,3-phenylene)bis-1H-pyrrole-2,5-dione 3006-93-7	3006-93-7	0.0200	6.5000%	117	0.0100%
		Acrylic acid, 2-[methyl[(1,1,2,2,3,3,4,4,4-nonafluorobutyl) sulfonyl]amino]ethyl ester, telomer with 3-mercaptopropanediol, 2-me	1017237-78-3	0.0010	0.5000%	9	0.0000%
Die	Circuit	Silicon	7440-21-3	1.6190	100.0000%	11,980	1.2000%
Wire	Interconnect	Copper	7440-57-5	0.0300	98.2500%	216	0.0200%
		Palladium	7440-05-3	0.0010	1.7500%	4	0.0050%
Mold Compound	Encapsulation	Silica Fused	60676-86-0	56.8600	87.0000%	415327	41.5300%
		Epoxy resin	Trade Secret	3.9200	6.0000%	28643	2.8600%
		Epoxy, Cresol Novolac	29690-82-2	1.3100	2.0000%	9548	0.9500%
		Phenol Novolac	Trade Secret	3.200	4.9000%	23,392	2.3400%
		Carbon Black	1333-86-4	0.0700	0.1000%	477	0.0500%

Package Weight (mg): 136.9000

% Total: 100.0000

B2. MATERIAL COMPOSITION (Note 3)

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Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

USING G770HCD Mold Compound

Material	Purpose of Use	Substance Composition	CAS Number	Weight by mg	% Weight of Substance per Homogeneous Material	PPM	% Weight of Substance per Package
Leadframe	Base Material	Cu	7440-50-8	57.4700	92.4400%	416504	41.6500%
		Fe	7439-89-6	1.4600	2.3500%	10588	1.0600%
		Zn	7440-66-6	0.0800	0.1300%	563	0.0600%
		P	7723-14-0	0.0500	0.0800%	372	0.0400%
		Ag	7440-22-4	3.1100	5.0000%	22528	2.2500%
Lead Finish	External Plating	Sn	7440-31-5	7.4590	100.0000%	54058	5.4100%
Die Attach	Adhesive	Silver	7440-22-4	0.1800	73.0000%	1307	0.1300%
		Exo-1,7,7-trimethylbicyclo[2.2.1] hept-2-yl methacrylate	7534-94-3	0.0500	20.0000%	358	0.0400%
		1,1-(1,3-phenylene)bis-1H-pyrrole-2,5-dione	3006-93-7	0.0200	6.5000%	116	0.0100%
		Acrylic acid, 2[methyl]1,1,2	1017237-78-3	0.0010	0.5000%	8	0.0000%
Die	Circuit	Silicon	7440-21-3	2.7240	100.0000%	19742	1.9600%
Wire	Interconnect	Cu	7440-50-8	0.0300	98.2500%	214	0.0200%
		Pd	7440-05-3	0.0050	1.7500%	4	0.0000%
Mold Compound	Encapsulation	Silica Fused	60676-86-0	59.1400	90.5000%	428642	42.8600%
		Phenol Resin	Trade Secret	3.0700	4.7000%	22261	2.2300%
		Epoxy Resin	Trade Secret	3.0700	4.7000%	22261	2.2300%
		Carbon Black	1333-86-4	0.0700	0.1000%	474	0.0500%

Package Weight (mg): **137.9890**

% Total: **100.0000%**

B3. MATERIAL COMPOSITION (Note 3)

USING G600 Mold Compound , Au wire,8600D/A

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Note 4: Actual testing performed on package family basis. Engineering calculations were applied to derive individual package data.

Material	Purpose of Use	Substance Composition	CAS Number	Weight by mg	% Weight of Substance per Homogeneous Material	PPM	% Weight of Substance per Package
Leadframe	Base Material	Cu	7440-50-8	60.5600	97.4100%	442372	44.2400%
		Fe	7439-89-6	1.4600	2.3500%	10672	1.0700%
		Zn	7440-66-6	0.0800	0.1300%	568	0.0600%
		P	7723-14-0	0.0500	0.0800%	375	0.0400%
		Ag	7440-22-4	0.0200	0.0300%	136	0.0100%
Lead Finish	External Plating	Sn	7440-31-5	7.4590	100.0000%	54486	5.4500%
Die Attach	Adhesive	Silver	7440-22-4	0.2000	81.5000%	1470	0.1500%
		(Octahydro-4,7-methano-1Hindenediyl)(methylene)diacrylate	42594-17-2	0.0100	6.0000%	108	0.0100%
		Exo-1,7,7-trimethyibicyclo[2.2.1]hept-2-yl methacrylate	7534-94-3	0.0100	6.0000%	108	0.0100%
		Isobomyl acrylate	5888-33-5	0.0010	6.0000%	108	0.0100%
		Bis(.alpha.,.alpha.-Dimethylx	80-45-3	0.0000	0.5000%	10	0.0000%
Die	Circuit	Silicon	7440-21-3	1.6600	100.0000%	11980	1.2000%
Wire	Interconnect	Au	7440-57-5	0.0300	100.0000%	220	0.0200%
Mold Compound	Encapsulation	Silica Fused	60676-86-0	56.8600	87.0000%	415327	41.5300%
		Phenol Resin	Trade Secret	3.2000	4.9000%	23392	2.3400%
		Epoxy Resin	Trade Secret	3.9200	6.0000%	28643	2.8600%
		Carbon Black	1333-86-4	0.0700	0.1000%	477	0.0500%
		Epoxy Cresol Novolec	29690-82-2	1.3100	2.0000%	9548	0.9500%

Package Weight (mg): 136.9000

% Total: 100.0000%

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II. DECLARATION OF PACKAGING INDIRECT MATERIALS

Type	Material	Lead PPM	Cadmium PPM	Cr VI PPM	Mercury PPM	PBB PPM	PBDE PPM	Analysis Report (Note2)
Tube	Plastic Tube	<5.0	<5.0	<5.0	<5.0	<5.0	<5.0	CoA-PLTB-R
	End Plug	<5.0	<5.0	<5.0	<5.0	<5.0	<5.0	CoA-EPLG-R
Tape and Reel	Carrier Tape	<5.0	<5.0	<5.0	<5.0	<5.0	<5.0	CoA-CART-R
Others	Moisture Barrier Bag	<5.0	<5.0	<5.0	<5.0	<5.0	<5.0	CoA-MBBG-R
	Dessicant	<5.0	<5.0	<5.0	<5.0	<5.0	<5.0	CoA-DESS-R
	HIC	<5.0	<5.0	<5.0	<5.0	<5.0	<5.0	CoA-HIC-R
	Bubble Pack	<5.0	<5.0	<5.0	<5.0	<10.0	<10.0	CoA-BUBB-R
	Carton Label	<10.0	<5.0	<5.0	<5.0	<5.0	<5.0	CoA-CRTN-R
	Inner Label	<10.0	<5.0	<5.0	<5.0	<5.0	<5.0	CoA-LBL-R
	Shielding Bag	<5.0	< 5.0	< 5.0	< 5.0	< 5.0	< 5.0	CoA-SBAG-R

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Document History Page

Document Title: 8L-SOIC EIAJ PB-FREE PACKAGE MATERIAL DECLARATION DATASHEET
Document Number: 001-96076

Rev.	ECN No.	Orig. of Change	Description of Change
**	4624611	PRCH	New release
*A	4741102	PRCH	Add G600 with Au wire
*B	5611996	HLR	Changed Cypress Logo.
		SLLO	Removed Distribution and Posting from the document history page.

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